



E01C-ML01SP2 User Manual

SI24R1+ 2.4GHz 100mW SPI SMD wireless module



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Chapter1. Overview

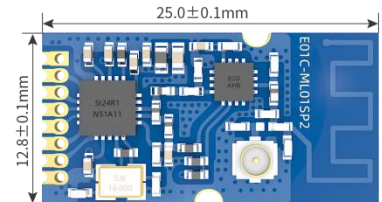
1.1 Brief introduction

E01C-ML01SP2 is a small size, self-contained PCB antenna and a 2.4GHz patch type wireless module with a maximum transmission power of 100mW based on the domestic SI24R1.

Built-in power amplifier (PA) and low noise amplifier (LNA) on the original basis, so that the maximum transmission power reaches 100mW, while the receiving sensitivity is further improved, and the overall communication stability is less than there is no power amplifier and low noise amplifier The products have been greatly improved.

This product has obtained FCC, CE, RoHS and other authoritative certification reports at home and abroad, and uses industrial-grade high-precision 16MHz crystal oscillator.

Since E01C-ML01SP2 is a pure radio frequency transceiver module, it needs to use MCU driver or use a dedicated SPI debugging tool.



1.2 Features

- Ultra-small size, only 12.8x25mm;
- RFX2401C power amplifier scheme, the maximum transmission power is 100mW, and the software is multi-level adjustable;
- Under ideal conditions, the communication distance can reach 1.8km;
- At the same time, it has PCB onboard antenna and IPX interface, users can choose to use according to their own needs;
- Professional radio frequency shield, anti-interference and anti-static;
- Support the global license-free ISM 2.4GHz frequency band;
- Support 2Mbps, 1Mbps and 250kbps air rate;
- 125 communication channels to meet application requirements such as multipoint communication, grouping, and frequency hopping;
- Connect with MCU through SPI interface, rate 0~10Mbps;
- Support 2.0~3.6V power supply, power supply greater than 3.3V can guarantee the best performance;
- Industrial standard design, support -40~+85°C long time use;

1.3 Application

- Wearable device;
- Smart home and industrial sensors, etc.;
- Security system, positioning system;
- Wireless remote control, UAV;
- Wireless game remote control;

- Healthcare products;
- Wireless voice, wireless headset;
- Automotive industry applications.

Chapter2. Specifications

2.1 Limit parameter

Main parameter	Performance		备注
	Min.	Max.	
Power supply (V)	0	3.6	Voltage over 3.6V will cause permanent damage to module
Blocking power (dBm)	-	10	Chances of burn is slim when modules are used in short distance
Operating temperature (°C)	-40	85	Industrial grade

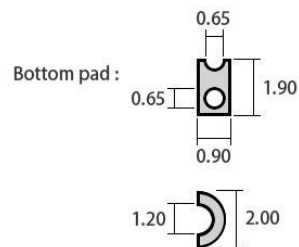
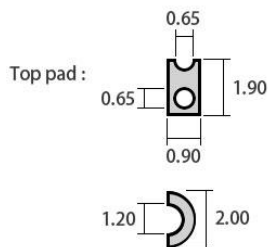
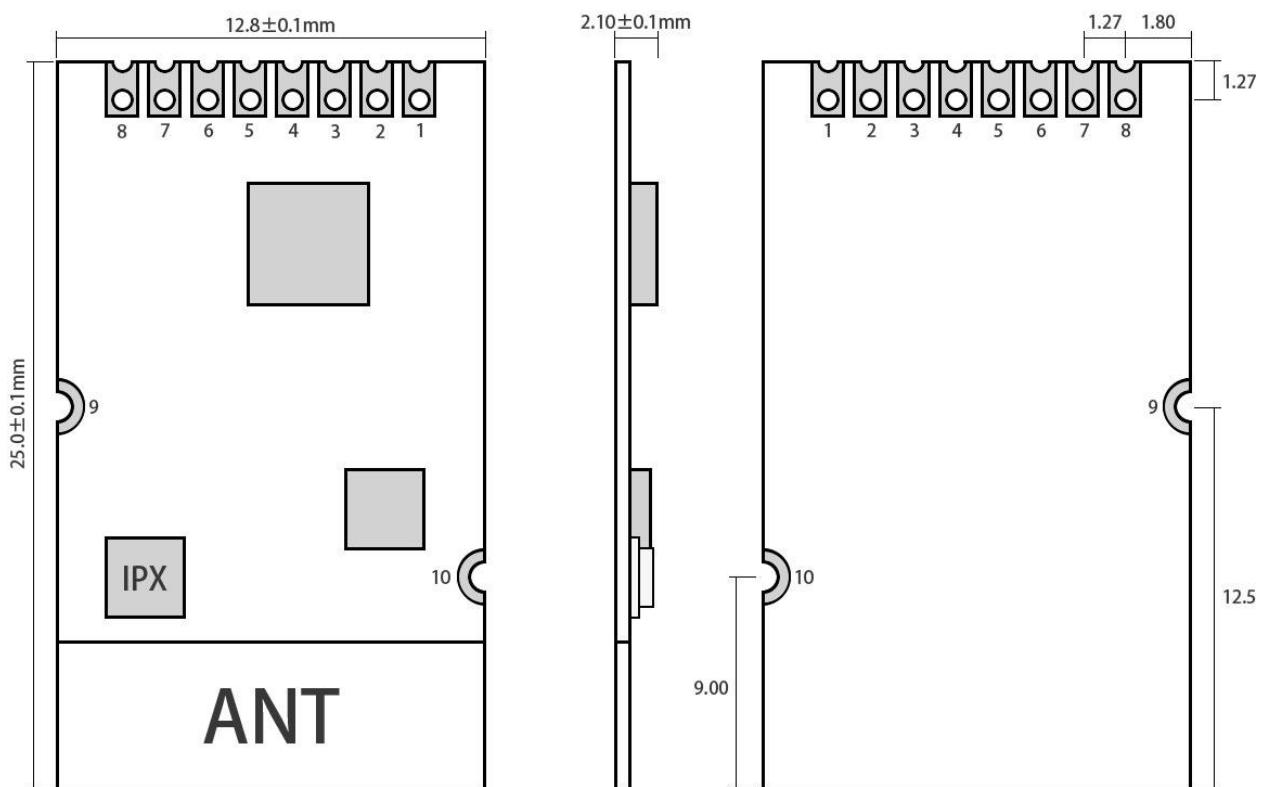
2.2 Operating parameter

Main parameter	Performance			Remark
	Min.	Typ.	Max.	
Operating voltage (V)	2.0	3.3	3.6	$\geq 3.3V$ ensures output power
Communication level (V)		3.3		For 5V TTL, it may be at risk of burning down
Operating temperature (°C)	-40	-	85	Industrial design
Operating frequency (GHz)	2.4	-	2.525	Support ISM band
Power consumption	Tx current	120		Instantaneous power consumption
	Rx current	28.5		
	Sleep current(μA)	2		Software is shut down
Max Tx power (dBm)	19.7	20	20.2	
Receiving sensitivity (dBm)	-96.5	-96	-97.5	Air data rate is 250kbps
Air data rate (bps)	250k	-	2M	Controlled via user's programming

Main parameter	Description	Remark
Reference distance	1800m	Test condition: clear and open area, antenna gain: 5dBi, antenna height: 2.5m, air data rate: 250kbps
FIFO	32Byte	Max length transmitted each time
Crystal frequency	16MHz	

Modulation	GFSK	
Package	SMD	
Connector	1.27mm pin header	
Communication interface	SPI	0~10Mbps
Size	12.8 * 25mm	With out SMA
Antenna	PCB/IPEX	The factory default PCB antenna, the equivalent impedance is about 50Ω

Chapter3. Size and pin definition



Pad quantity : 10
Unit: mm

Pin No.	Pin item	Pin direction	Pin application
1	VCC		The power supply must be between 2.0~3.6V
2	CE	Input	Module control pin
3	CSN	Input	Module chip select pin, used to start a SPI communication

4	SCK	Input	Module SPI bus clock
5	MOSI	Input	Module SPI data input pin
6	MISO	Output	Module SPI data output pin
7	IRQ	Output	Module terminal signal output, active low
8	GND		Ground wire, connected to the power reference ground
9	GND		Ground wire, connected to the power reference ground
10	GND		Ground wire, connected to the power reference ground

Chapter4. Basic operation

4.1 Hardware design

- It is recommended to use a DC stabilized power supply. The power supply ripple factor is as small as possible, and the module needs to be reliably grounded;
- Please pay attention to the correct connection of the positive and negative poles of the power supply. Reverse connection may cause permanent damage to the module;
- Please check the power supply to ensure it is within the recommended voltage otherwise when it exceeds the maximum value the module will be permanently damaged;
- Please check the stability of the power supply, the voltage can not be fluctuated frequently;
- When designing the power supply circuit for the module, it is often recommended to reserve more than 30% of the margin, so the whole machine is beneficial for long-term stable operation;
- The module should be as far away as possible from the power supply, transformers, high-frequency wiring and other parts with large electromagnetic interference;
- High-frequency digital routing, high-frequency analog routing, and power routing must be avoided under the module. If it is necessary to pass through the module, assume that the module is soldered to the Top Layer, and the copper is spread on the Top Layer of the module contact part(well grounded), it must be close to the digital part of the module and routed in the Bottom Layer;
- Assuming the module is soldered or placed over the Top Layer, it is wrong to randomly route over the Bottom Layer or other layers, which will affect the module's spurs and receiving sensitivity to varying degrees;
- It is assumed that there are devices with large electromagnetic interference around the module that will greatly affect the performance. It is recommended to keep them away from the module according to the strength of the interference. If necessary, appropriate isolation and shielding can be done;
- Assume that there are traces with large electromagnetic interference (high-frequency digital, high-frequency analog, power traces) around the module that will greatly affect the performance of the module. It is recommended to stay away from the module according to the strength of the interference. If necessary, appropriate isolation and shielding can be done.
- If the communication line uses a 5V level, a 1k-5.1k resistor must be connected in series (not recommended, there is still a risk of damage);
- Try to stay away from some physical layers such as TTL protocol at 2.4GHz , for example: USB3.0;
- The mounting structure of antenna has a great influence on the performance of the module. It is necessary to ensure that the antenna is exposed, preferably vertically upward. When the module is mounted inside the case, use a good antenna extension cable to extend the antenna to the outside;

- The antenna must not be installed inside the metal case, which will cause the transmission distance to be greatly weakened.
- Conductors or other sources of interference should be avoided around the onboard PCB antenna.

4.2 Software editing

- The drive mode of this module SI24R1+PA+LNA is completely equivalent to SI24R1, and users can operate according to the SI24R1 chip manual (see SI24R1 manual for details);

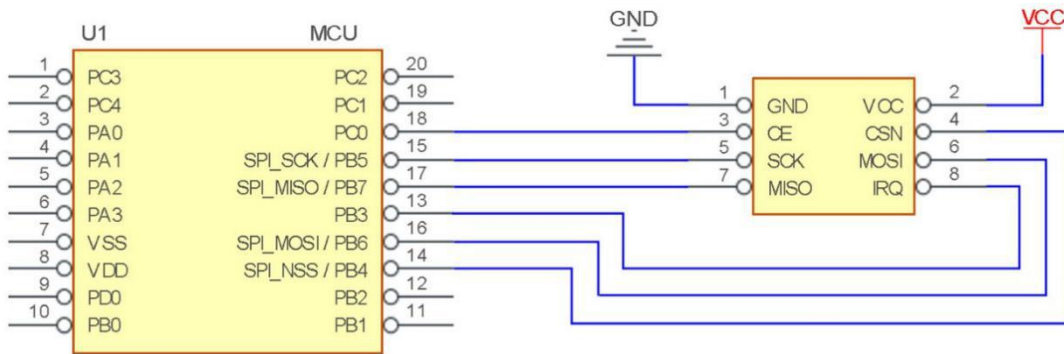
Power bin:

SI24R1 register setting table:

Address(Hex)	Mnemonic	Bit	Reset Value	Description
06	RF_SETUP			RF configuration
	RF_PWR	2:0	110	Set TX power 111:7dBm 110:4dBm 101:3dBm 100:1dBm 011:0dBm 010:-4dBm 001:-6dBm 000:-12dBm

- 011: Pre-stage-0dBm, Output 20dBm;
- 010: Pre-stage-4dBm, Output 16dBm;
- 011: Pre-stage-6dBm, Output 12dBm;
- 000: Pre-stage-12dBm, Output 6dBm;
- IRQ is an interrupt pin, which can be used to wake up the microcontroller and achieve fast response; it can be disconnected, and the interrupt status can be obtained by SPI query (not recommended, not conducive to overall power consumption, and low efficiency);
- CE can be connected to the high level for a long time, but the module must be set to POWER DOWN power-down mode when writing the register. It is recommended that CE be controlled by the MCU pin;
- The CE pin is connected to the LNA enable pin. When CE=1, the LNA is turned on, and when CE=0, the LNA is turned off. This operation is completely consistent with the transceiver mode of nRF24L01; that is, the user does not need to care about LNA operation at all;
- If the user needs to answer automatically, the CE pin must be kept high during the transmission process, and the high level time cannot be longer than 10us as mentioned in the nRF24L01+ manual. The correct operation is: CE=1 to trigger the transmission. After knowing that the transmission is completed, CE=0, instead of CE=0 after 10us. The reason is: After SI24R1+ is sent, it will immediately switch to receiving mode. At this time, if CE= 0, the LNA has been turned off, which is not conducive to receiving sensitivity.

Chapter5. Circuit diagram



Chapter6. FAQ

6.1 Communication range is too short

- When there is a straight line communication obstacle, the communication distance will be attenuated accordingly;
- Temperature, humidity, and co-frequency interference will increase the communication packet loss rate;
- The ground absorbs and reflects radio waves, and the test results near the ground are poor;
- Sea water has a strong ability to absorb radio waves, so the seaside test results are poor;
- If there is a metal object near the antenna or placed in a metal shell, the signal attenuation will be very serious;
- The power register setting is wrong, the air speed setting is too high (the higher the air speed, the closer the distance);
- The low voltage of the power supply at room temperature is lower than the recommended value, the lower the voltage, the lower the power output;
- The poor matching degree of the antenna and the module or the quality of the antenna itself.

6.2 Module is easy to damage

- Please check the power supply to ensure that it is within the recommended power supply voltage. If it exceeds the maximum value, it will cause permanent damage to the module;
- Please check the stability of the power supply, the voltage should not fluctuate greatly and frequently;
- Please ensure anti-static operation during installation and use, and high-frequency components are electrostatically sensitive;
- Please ensure that the humidity during installation and use should not be too high, and some components are humidity sensitive devices;
- If there is no special requirement, it is not recommended to use at too high or too low temperature.

6.3 BER(Bit Error Rate) is high

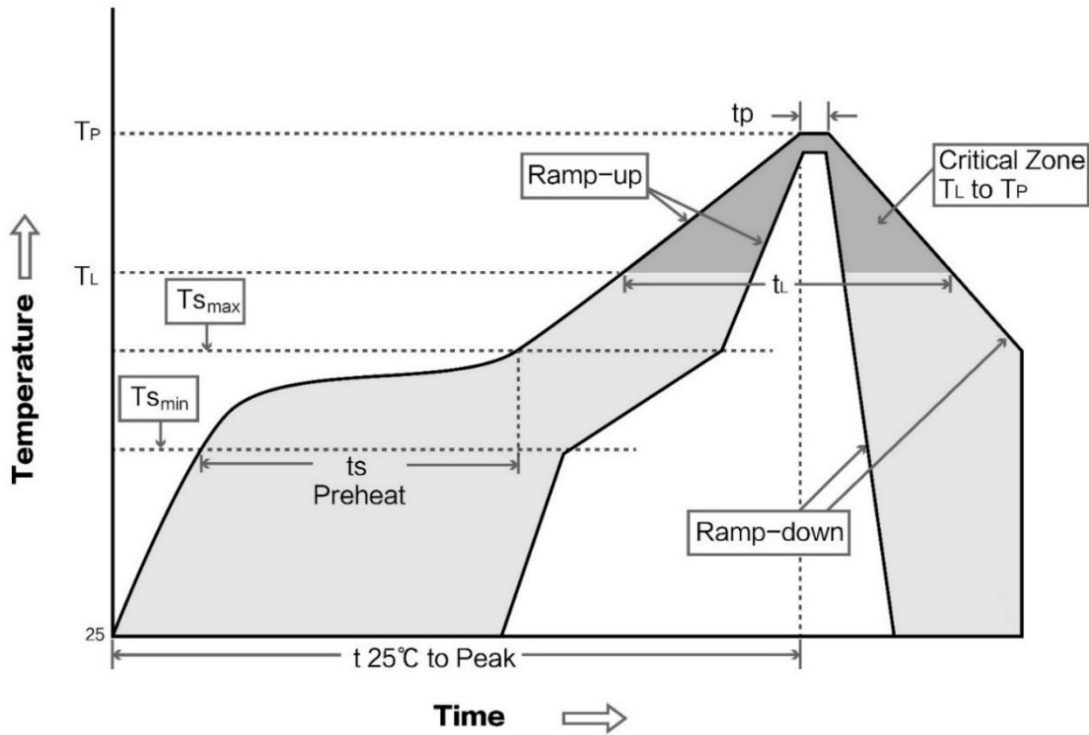
- There is co-frequency signal interference nearby, stay away from the interference source or modify the frequency and channel to avoid interference;
- The clock waveform on SPI is not standard, check whether there is interference on the SPI line, and the SPI bus line should not be too long;
- Unsatisfactory power supply may also cause garbled codes. Ensure the reliability of the power supply;
- Poor or too long extension cords and feeders will also cause high bit error rates.

Chapter7. Soldering guidance

7.1 Reflow soldering temperature

Profile Feature	Curve characteristics	Sn-Pb Assembly	Pb-Free Assembly
Solder Paste	Solder paste	Sn63/Pb37	Sn96.5/Ag3/Cu0.5
Preheat Temperature min (T _{smin})	Min preheating temp.	100°C	150°C
Preheat temperature max (T _{smax})	Mx preheating temp.	150°C	200°C
Preheat Time (T _{smin} to T _{smax})(ts)	Preheating time	60-120 sec	60-120 sec
Average ramp-up rate(T _{smax} to T _p)	Average ramp-up rate	3°C/second max	3°C/second max
Liquidous Temperature (TL)	Liquid phase temp.	183°C	217°C
Time (t _L) Maintained Above (TL)	Time below liquid phase line	60-90 sec	30-90 sec
Peak temperature (T _p)	Peak temp.	220-235°C	230-250°C
Average ramp-down rate (T _p to T _{smax})	Average ramp-down rate	6°C/second max	6°C/second max
Time 25°C to peak temperature	Time to peak temperature for 25°C	6 minutes max	8 minutes max

7.2 Reflow soldering curve



Chapter8. Related models

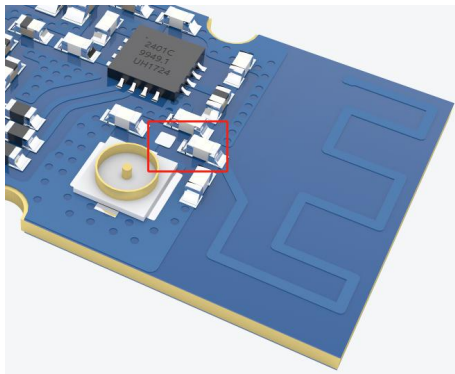
Model	IC	Frequency	Power	Distance	Package	Antenna
		Hz	dBm	m		
E01-ML01S	nRF24L01+	2.4G	0	100	SMD	PCB
E01-ML01D	nRF24L01+	2.4G	0	100	DPI	PCB
E01-ML01IPX	nRF24L01+	2.4G	0	200	SMD	IPEX
E01-2G4M13S	nRF24L01+	2.4G	13	1200	SMD	PCB
E01-ML01SP2	nRF24L01+	2.4G	20	1800	SMD	PCB/IPEX
E01-ML01SP4	nRF24L01+	2.4G	20	2000	SMD	IPEX
E01-ML01DP4	nRF24L01+	2.4G	20	1800	DPI	PCB
E01-ML01DP5	nRF24L01+	2.4G	20	2500	DPI	SMA-K
E01-2G4M27D	nRF24L01+	2.4G	27	5000	DPI	SMA-K

All wireless modules of the E01 series can communicate with each other

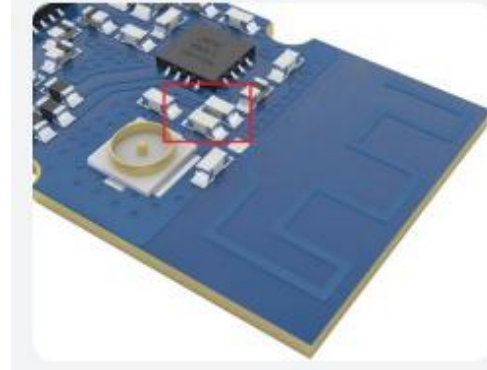
Chapter9. Antenna Guide

Products Model	Type	Frequency	Gain	Size	Feeder	Interface	Feature
		Hz	dBi	mm	cm		
TX2400-NP-5010	Flexible antenna	2.4G	2.0	10x50	-	IPEX	Flexible FPC soft antenna
TX2400-JZ-3	Glue stick antenna	2.4G	2.0	30	-	SMA-J	Ultra-short straight, omnidirectional antenna
TX2400-JZ-5	Glue stick antenna	2.4G	2.0	50	-	SMA-J	Ultra-short straight, omnidirectional antenna
TX2400-JW-5	Glue stick antenna	2.4G	2.0	50	-	SMA-J	Fixed bending, omnidirectional antenna
TX2400-JK-11	Glue stick antenna	2.4G	2.5	110	-	SMA-J	Bendable glue stick, omnidirectional antenna
TX2400-JK-20	Glue stick antenna	2.4G	3.0	200	-	SMA-J	Bendable glue stick, omnidirectional antenna
TX2400-XPL-150	Suction cup antenna	2.4G	3.5	150	150	SMA-J	Small suction cup antenna, cost-effective

Chapter10. Antenna selection

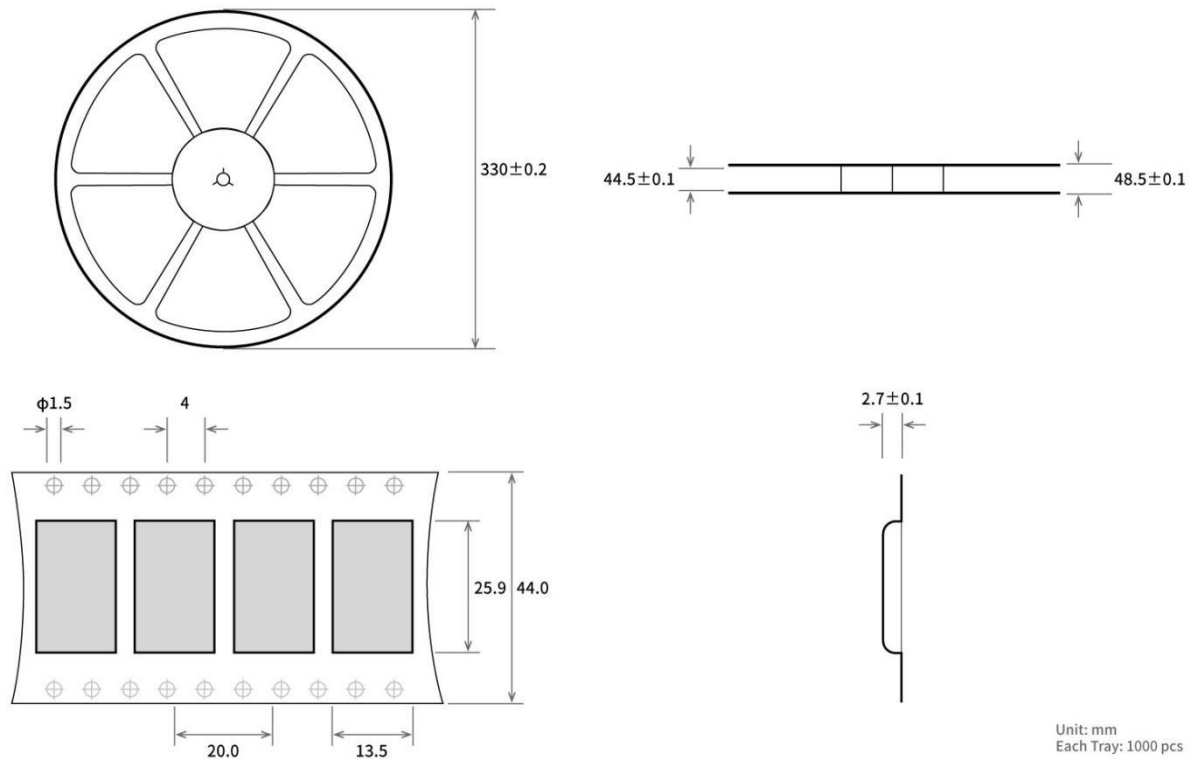


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Chapter11. Bulk packaging



Revision history

Version	Date	Description	Issued by
1.0	2017-11-15	initial version	huaa
1.1	2018-5-22	Content increase	huaa
1.2	2018-9-13	Manual split	huaa
1.3	2019-1-26	Content increase	Ray
1.4	2019-11-06	Fix mistakes	Ren
1.5	2019-11-18	Fix mistakes	Ren

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